

# **CG7 Series**









#### **Agency Approvals**

AGENCY	AGENCY FILE NUMBER		
<b>71</b>	E128662		
<b>71</b> 2	E320116		

#### Two Electrode GDT Graphical Symbol



## **Additional Information**







Samples

## **Description**

The Littelfuse CG7 series GDT is a miniature surface mount device with a 1kA 8/20µS surge rating. Its low insertion loss and thus low offstate capacitance makes it compatible with high bandwidth applications up to the GHz RF range. This GDT's crowbarring characteristic protects sensitive ICs from surges as defined in ITU K.20/21/45 Basic and Enhanced Recommendations, GR-1089-CORE first level lightning Port Type 1 and 3, and IEC 61000-4-5 2nd edition. It is hermetically sealed using non-radioactive materials Classes 1-3 and some Class 4 & 5 cases and is thus environmentally safe. Its 2.8mm diameter size makes it the world's smallest two-electrode single chamber GDT available.

#### **Features**

- RoHS compliant and Lead-free
- Excellent Surge
  Withstanding Capability
- Excellent response to fast rising transients.
- Ultra Low Insertion Loss and low off-state capacitance for GHz bandwidth compatibility
- Ultra small devices offered in SMD package

- 1kA 8/20µS surge capability pulse as defined by IEC 61000-4-5 2<sup>nd</sup> edition
- Ultra Low capacitance (<0.3pF)</li>
- Voltage Range 75V to 470V
- UL recognized

## **Applications**

- Set top box
- Cable Modem
- Embedded Multimedia Terminal Adapter (EMTA)
- RF Connector
- Multimedia over Coax Alliance (MoCA)
- Base Station RF antenna transmitter
- G.Fast 106MHz and 212 MHz bandplans compatible
- CATV/Broadband equipment

- Data lines and Ethernet (up to 10GbE)
- Telecom line protection
- Broadband equipment
- xDSL equipment, including ADSL2, ADSL, VDSL, VDSL2 30a bandplan compatible
- IAD (Integrated Access Device)
- Aerospace and Automotive



#### **Electrical Characteristics**

	Device Specifications (at 25°C)							Life Ratings					
Part		Breakd in Volts @100V/s	S	Impulse Break- down in Volts (@100V/µs)	Impulse Break- down In Volts (@1kV/µs)	Insulation Resistance	Capaci- tance (@1MHz)	Max Impulse Discharge Current (8/20µs)	Max Impulse Discharge Current (10/700µs)	AC Dischage Current (9 cycle @50Hz)	DC Holdover Voltage (<150ms)	Impulse Life (8/20µs) (100A)	
Number	MIN	TYP	MAX	MAX		MIN	MAX			MIN		MIN	
CG775	60	75	90	600	700	160@50\/	1GΩ@50V				52V		
CG790	72	90	108	600	700	1GΩ@100V					52V		
CG7120	96	120	144	600	700						80V		
CG7150	120	150	180	600	700		0.25	10 Shots			80V		
CG7200	160	200	240	600	700				0 2mf	(@1kA) <sup>1</sup>	10 Shots	1A	135V
CG7230	186	230	276	600	700		1GΩ@100V 0.3pf	1 Shot	(@ 100A/4kV) <sup>2</sup>	IA	135V	Shots	
CG7250	200	250	300	600	700			at 2kA			135V		
CG7350	280	350	420	750	900							135V	1
CG7400	360	400	480	850	1000						135V		
CG7470	376	470	564	900	1100	1GΩ@250V					135V		

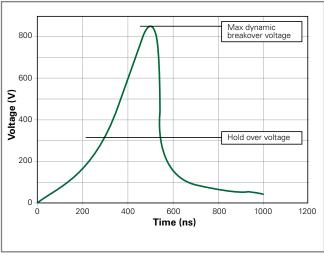
#### Notes:

- UL Pending for CG775 and CG7470.
- 1.  $5 \times (+)$  and  $5 \times (-)$  applications of 1kA 8/20 $\mu$ s sec.
- 2.  $5 \times (+)$  and  $5 \times (-)$  applications of 100A 10/700 $\mu$ s sec.

### **Product Characteristics**

Materials	Device Tin Plated 17.5 ± 12.5 Microns Construction: Ceramic Insulator	
Storage and Operational Temperature	-40 to +90°C	

# Voltage Vs. Time Characteristic



Note: Tested per 1kV/µs waveform

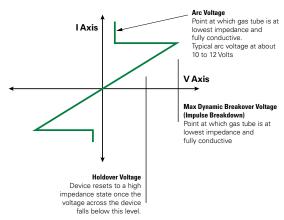
## **Typical Insertion Loss**

@1.0GHz = 0.02dB
@1.4GHz = 0.03dB
@1.8GHz = 0.05dB
@2.0GHz = 0.06dB
@2.4GHz = 0.07dB
@2.8GHz = 0.08dB
@3.1GHz = 0.09dB
@3.5GHz = 0.10dB
@4.0GHz = 0.12dB
<u> </u>

Note: Insertion data for customer reference only, application testing needed for verification.

### **V-I Characteristic Curve**

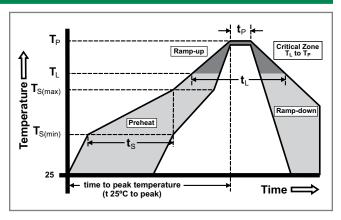
Characteristics of Gas Plasma -response to transient condition





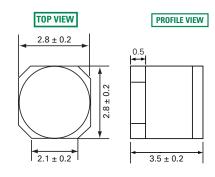
## **Soldering Parameters - Reflow Soldering (Surface Mount Devices)**

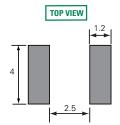
Reflow Co	ndition	Pb – Free assembly	
	-Temperature Min (T <sub>s(min)</sub> )	150°C	
Pre Heat	-Temperature Max (T <sub>s(max)</sub> )	200°C	
	-Time (Min to Max) (t <sub>s</sub> )	60 – 180 secs	
Average ra	amp up rate (LiquidusTemp k	3°C/second max	
T <sub>S(max)</sub> to T <sub>L</sub>	- Ramp-up Rate	5°C/second max	
Reflow	-Temperature (T <sub>L</sub> ) (Liquidus)	217°C	
nellow	-Temperature (t <sub>L</sub> )	60 – 150 seconds	
PeakTemp	perature (T <sub>P</sub> )	260 <sup>+0/-5</sup> °C	
Time with Temperate	in 5°C of actual peak ure (t <sub>p</sub> )	10 – 30 seconds	
Ramp-dov	vn Rate	6°C/second max	
Time 25°C	to peakTemperature (T <sub>P</sub> )	8 minutes Max.	
Do not exc	ceed	260°C	



## **Device Dimensions**

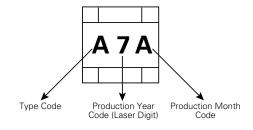
## Dimensions in millimeters





Recommended Soldering Pad Layout

## **Product Marking**



Type Code			
Α	<b>A</b> CG775		
В	CG790		
Т	CG7120		
С	CG7150		
0	CG7200		
D	CG7230		
R	CG7250		
G	CG7350		
ı	CG7400		
P	CG7470		

Month Code			
Α	January		
В	February		
С	March		
D	April		
E	May		
F	June		
G	July		
Н	August		
ı	September		
J	October		
K	November		
L	December		